

# Development of new RFQs for J-PARC

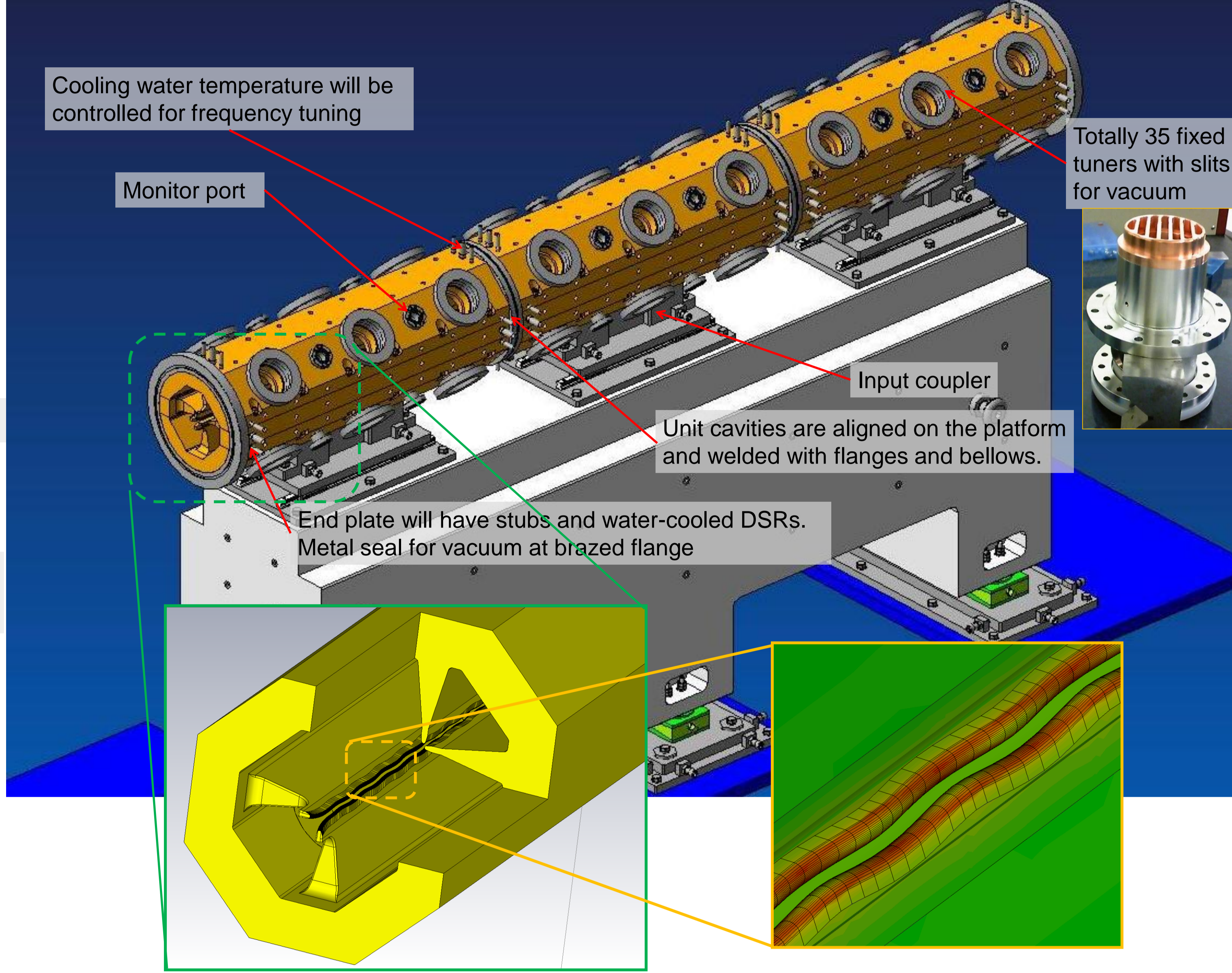
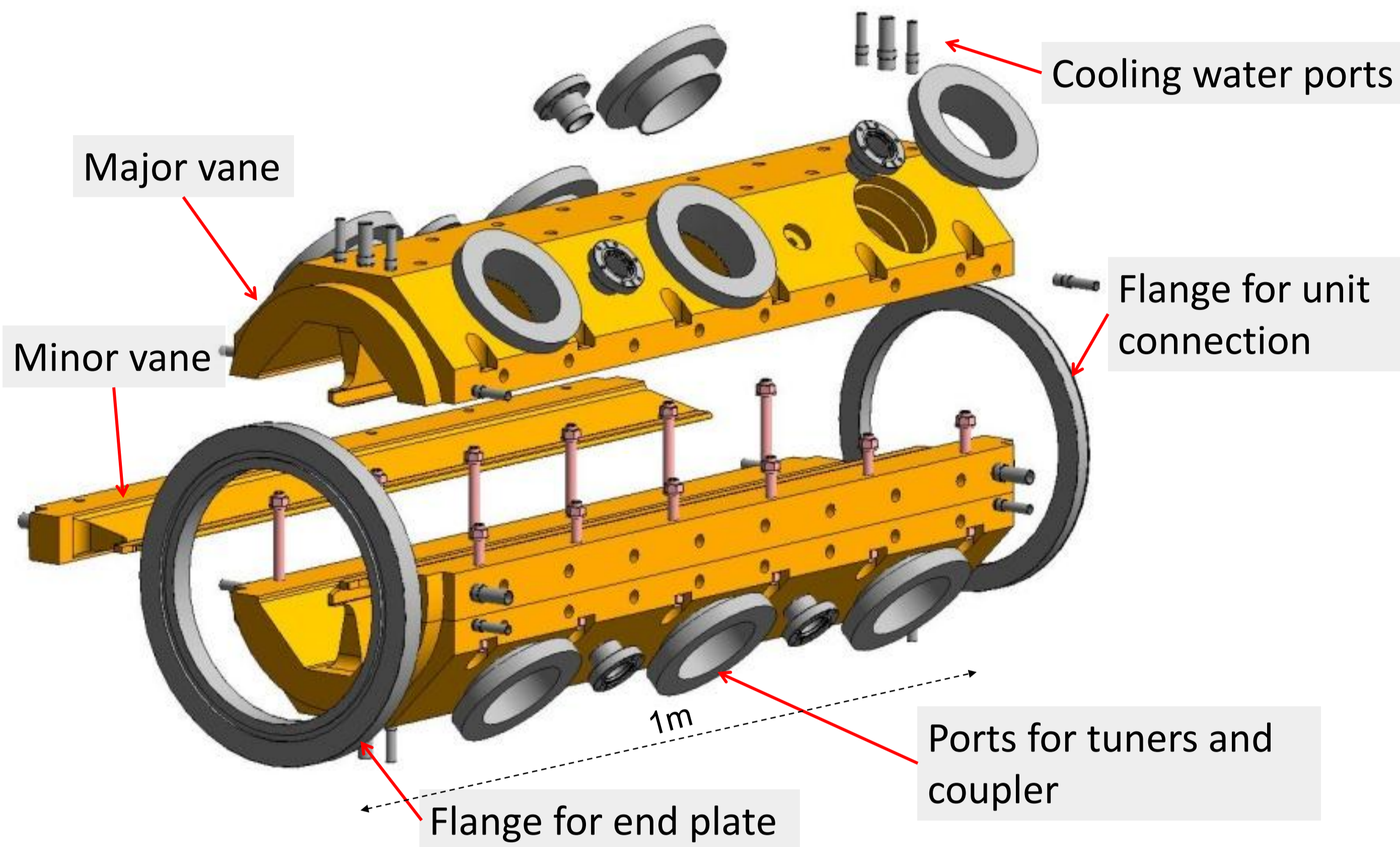
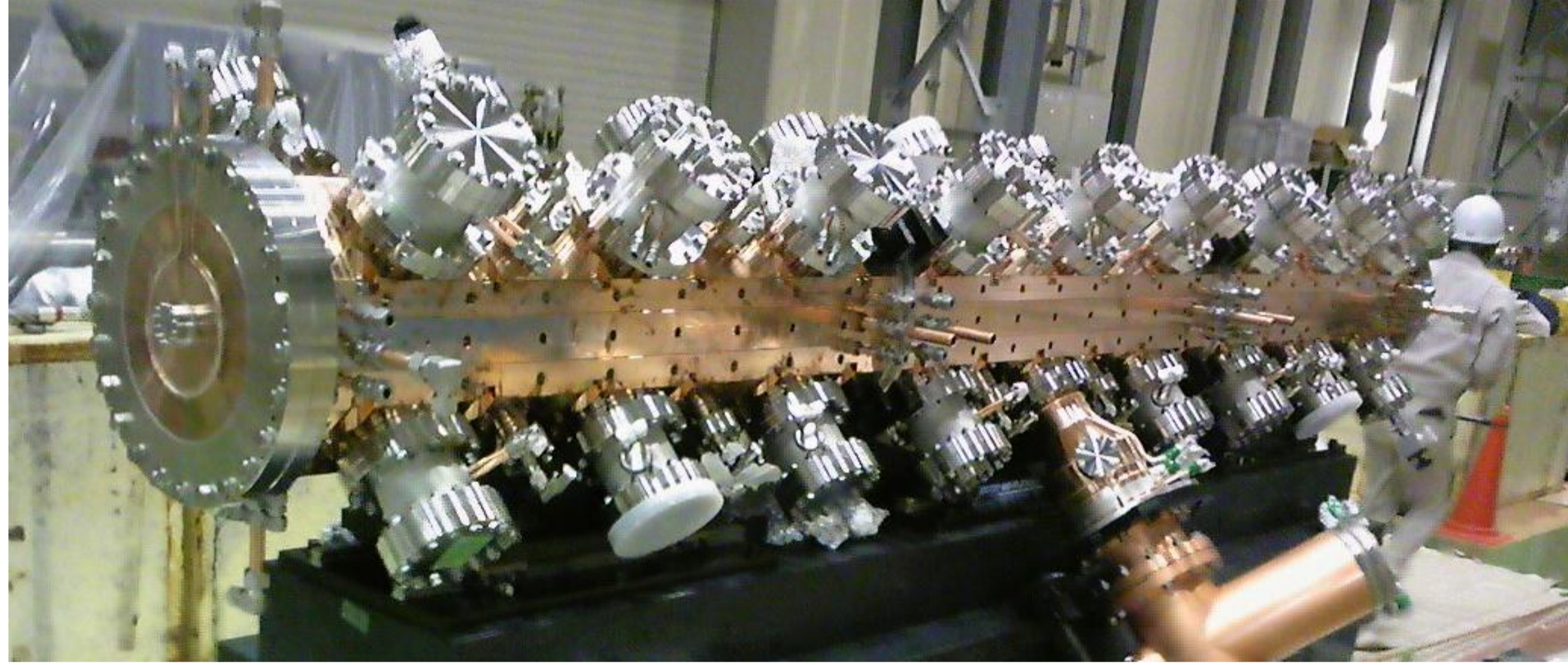
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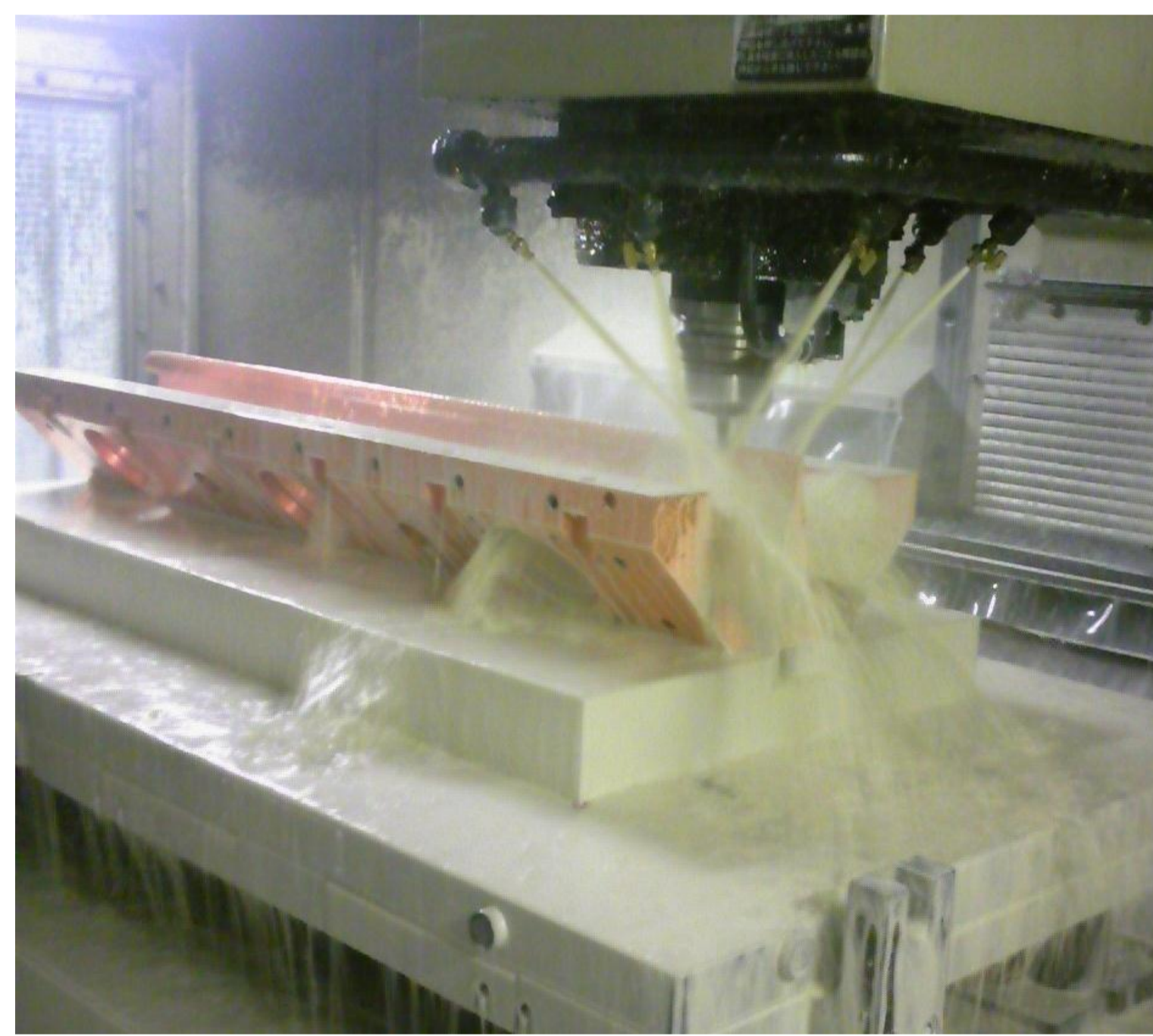
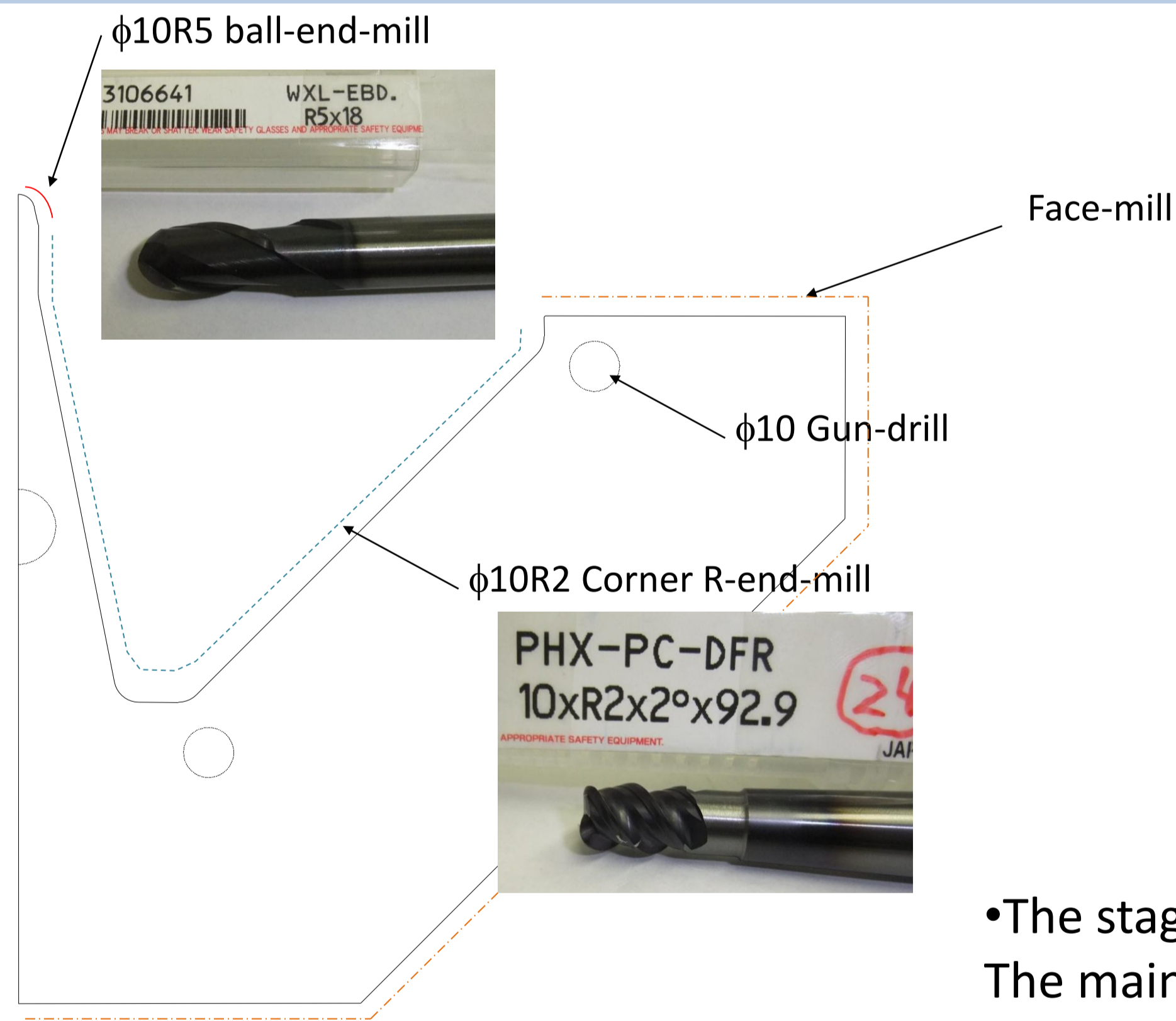
Parameters	RFQ I: operating	RFQ II: spare of RFQ I	RFQ III: in production
Beam current [mA]	30	←	50
Frequency [MHz]	324	←	←
Acceleration energy [MeV]	0.05 to 3	←	←
Vane length [m]	3.1	3.1	3.6
Inter-vane voltage[kV]	82.9	←	81
Max. surface field [MV/m]	31.6(1.77 Kilpatrick)	←	30.7(1.72 Kilpatrick)
Ave. bore radius [mm]	3.7	←	3.5
Vane-tip curvature [mm]	0.89r0 (3.293mm)	←	0.75r0(2.617mm)

Engineering design	RFQ I	RFQ II & III
Cavity material	OFC with 0.2% Ag	OFC + HIP(Hot Isostatic Pressing)
Joining method	Bolted with RF contactors in the vacuum chamber	Vanes, ports for vacuum, tuners, and flanges are brazed.
Vane machining	2D machining with wheel-shape formed bite	NC machining with conventional ball-end mill
Surface treatment	Acid wash	Chemical polishing

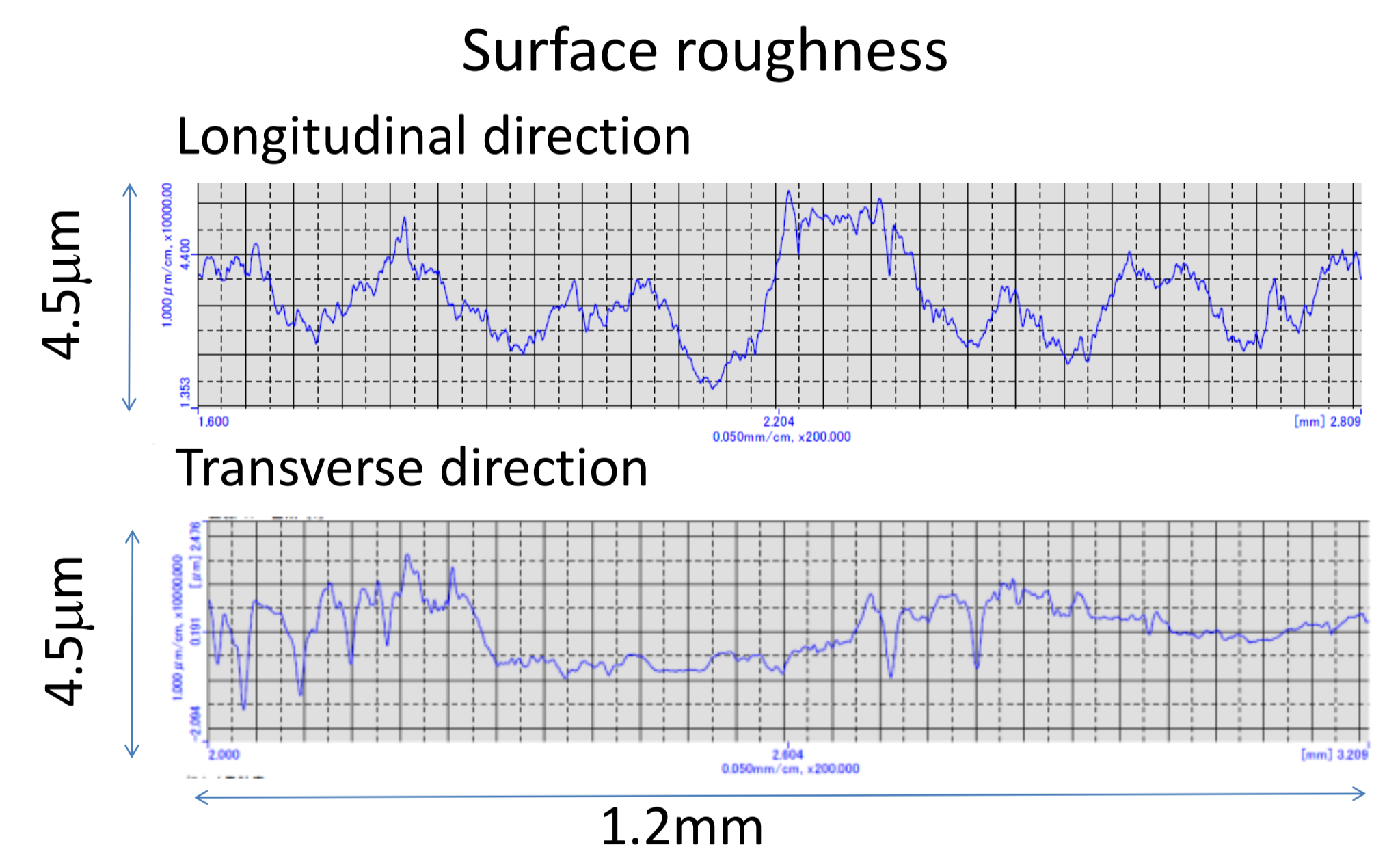
## RFQ II



## Vane machining using the ball-end mill



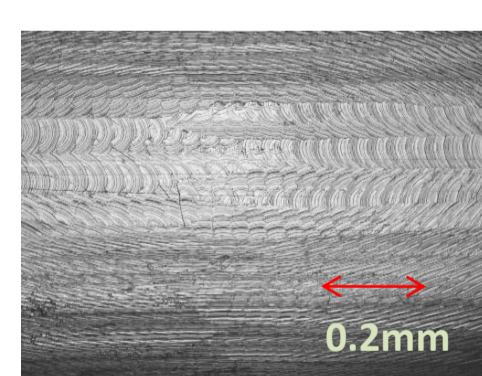
•The stage moves in a horizontal plane and the end-mill moves vertical. The main feed direction of the stage is the longitudinal direction.



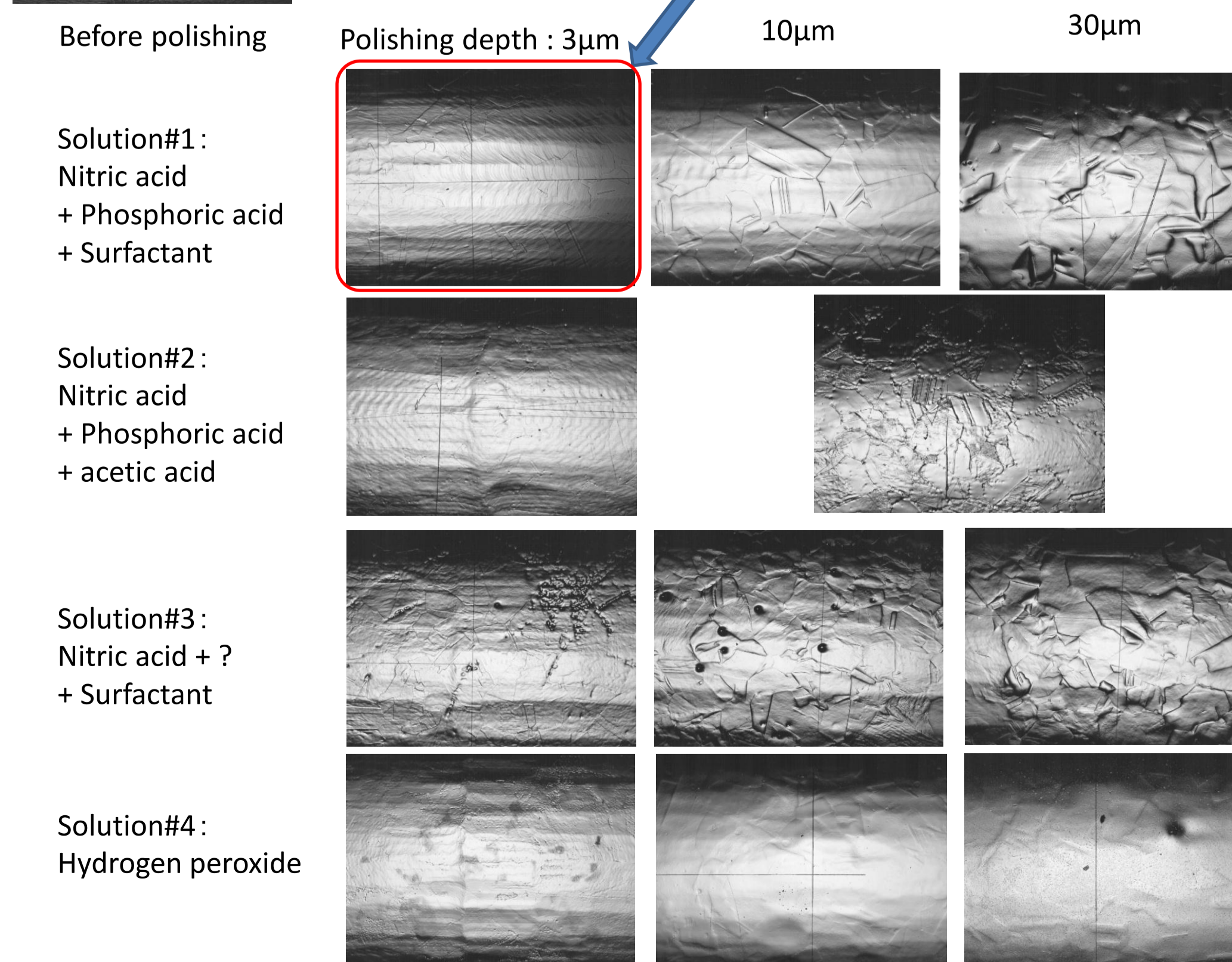
•The surface roughness is typically 0.8 µm (Ra)  
•The curvature of the ball-end mill is 5 mm.

## Surface treatment (chemical polishing)

process	Note
Cleaning	Water, methyl alcohol, methyl ethyl ketone Vane tip : running water Other : wiping
Masking	Taping, caulking Screw holes, contact face between support for handling
Degreasing	Alkaline solution Submerging
Acid wash	Sulfuric acid aqueous solution Submerging
Chemical polishing	Nitric acid + Phosphoric acid + Surfactant Submerging Polishing depth is controlled by temperature and time.
Acid wash	Sulfuric acid aqueous solution Submerging
Anticorrosion	Chromate solution Submerging
Cleaning /drying-out	Ultrapure water / drier Running water Air blow

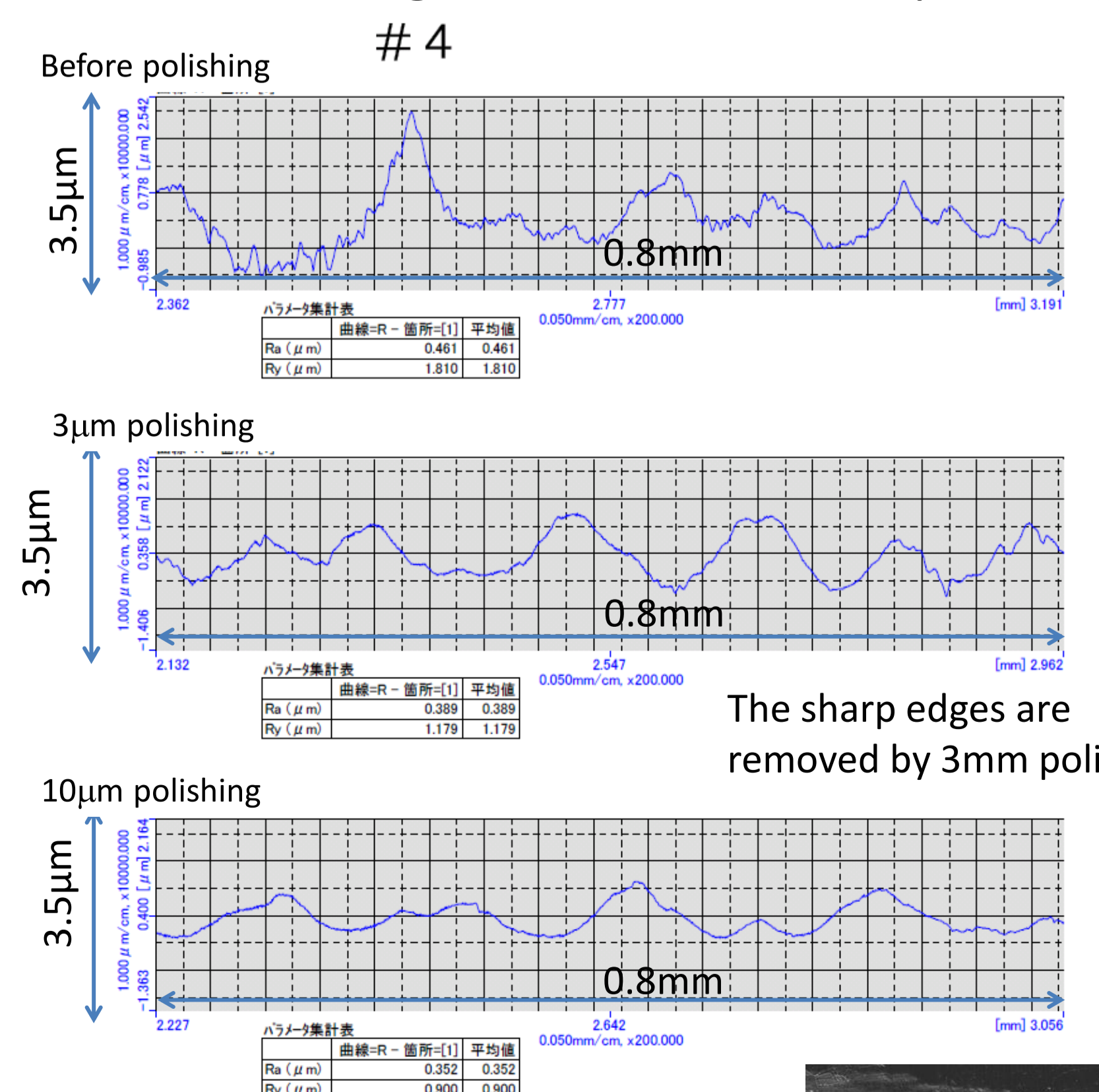


### Tested four kinds of solutions



Lightly-polished (less than 10 µm) surface seems well. Grain-boundary configuration appears at over-polished.

### Surface roughness after chemical polishing



The sharp edges are removed by 3mm polishing.

Outshoots are found only occasionally in the case of the solution #4. Our choice is the solution #1 with 3µm polishing.

